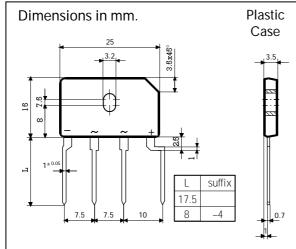
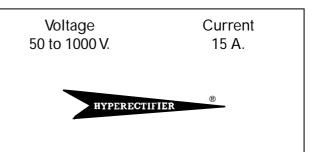


15 Amp. Glass Passivated Bridge Rectifier



- Mounting Instructions
- High temperature soldering guaranteed: 260 °C 10 sc.
- Recommended mounting torque: 8 Kg.cm.



- Glass Passivated Junction Chips.
- UL recognized under component index file number E320541.
- Lead and polarity identifications.
- · Case: Molded Plastic.
- Ideal for printed circuit board (P.C.B.).
- · High surge current capability.
- The plastic material carries U/L recognition 94 V-O.

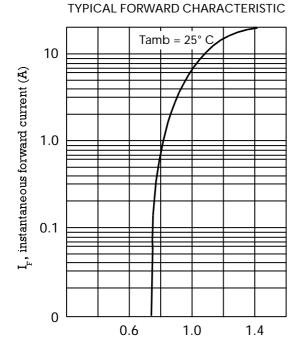
Maximum Ratings, according to IEC publication No. 134

		FBI15A 1M1	FBI15B 1M1	FBI15D 1M1	FBI15G 1M1	FBI15J 1M1	FBI15K 1M1	FBI15M 1M1
VRRM	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
V _{RMS}	Maximum RMS voltage (V)	35	70	140	280	420	560	700
I _{F(AV)}	Max. Average forward current with heatsink without heatsink	15.0 A at 75 °C 3.2 A at 25 °C						
IFSM	10 ms. peak forward surge current (Jedec Method)	200 A						
I ² t	Current squared time (rating for fusing) (1ms. <t<10ms. tc="25°C)</td"><td colspan="6">110 A² sec</td></t<10ms.>	110 A ² sec						
V _{DIS}	Dielectric strength (terminals to case, AC 1 min.)	2500 V						
T_{j}	Operating temperature range	– 55 to + 150 °C						
T_{stg}	Storage temperature range	− 55 to +150 °C						

Electrical Characteristics at Tamb = 25°C

V_{F}	Max. forward voltage drop per diode at $I_F = 7.5 \text{ A}$	1.10V
I _R	Max. instantaneous reverse current at V_{RRM}	5μΑ
	MAXIMUM THERMAL RESISTANCE	
R _{th (j-c)}	Junction-Case. With Heatsink.	2.2 °C/W
R _{th (j-a)}	Junction-Ambient. Without Heatsink.	22 °C/W



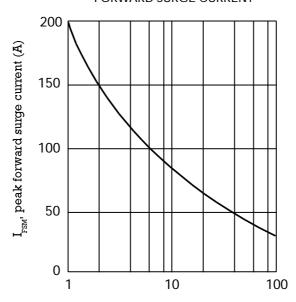


V_r, instantaneous forward voltage (V)

FORWARD CURRENT DERATING CURVE 15 12 9 In the atsink to the atsink t

Tamb, ambient temperature (°C)

MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



Number of cycles at 50 Hz.